IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	ials and Mfg Information				
upplier	r Information													
Company name*				ompany unique ID			Unique ID Authority				Response Date*			
nsemi										2023-06-08				
ontact N	ame	Title - Contact			F	Phone - Contact*				Email - Contact*				
?roduct-H	Env-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*	Title - Repre	Title - Representative			Phone - Representative*			Ema	Email - Representative*				
Product-Env-Stewards Product Enviro Com				iro Compliance	Compliance		NA			Proc	Product-Env-Stewards@onsemi.com			
	Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	Manufacturing	Manufacturing Site		UOM	Unit Type	
		GBU8KS BR GBU4SL GP		BR GBU4SL GPP	N 8A 800V		2023-06-08 TSCBE			3995.245	mg	Each		
lanufa	cturing Process Inform Terminal Plating / Grid Array N		Terminal Base	Alloy	-STD-020 MS	I. Poting	Dank Drogg	se Rody Tam	paratura May Tima	ot Dook Tamp	aratura Numbe	or of Patlow Cv	clas	
	8		U Allov NA		L Katilig	Peak Process Body Temperature Max Time a			1.	reak Temperature Number of Reflow Cycles seconds 3				
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minents)													
or more i	information regarding materia	l composition	nlease rafor t	n naga 1										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and/Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	15.0	mg	Supplier	Silicon (Si)	7440-21-3		15	mg
Die Attach Solder	15.025	mg	Supplier	Silver (Ag)	7440-22-4		0.3756	mg
			A	Lead (Pb)	7439-92-1	7a	13.8981	mg
			Supplier	Tin (Sn)	7440-31-5		0.7512	mg
Lead Frame	1799.6	mg	Supplier	Iron (Fe)	7439-89-6		2.6994	mg
			Supplier	Copper (Cu)	7440-50-8		1796.0009	mg
			Supplier	Phosphorus (P)	7723-14-0		0.8998	mg
Mold Compound-Black	2160.0	mg		Epoxy resin	proprietary data		108	mg
			Supplier	Phenolic Resin	Proprietary Data		162	mg
			Supplier	Carbon Black (C)	1333-86-4		10.8	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		324	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1555.2001	mg
Plating	5.62	mg	Supplier	Tin (Sn)	7440-31-5		5.62	mg